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SMP75

Trisil™ for telecom equipment protection

Features

- bidirectional crowbar protection
- voltage: 8 V
- low leakage current: $I_R = 2 \mu A$ max
- holding current: $I_H = 150$ mA min
- repetitive peak pulse current:
 $I_{PP} = 75$ A (10/1000 μs)

Benefits

- Trisils are not subject to ageing and provide a fail safe mode in short circuit for a better protection.
- This device can be used to help equipment to meet main standards such as UL1950, IEC 950 / CSA C22.2 and UL1459.
- Trisils have UL94 V0 approved resin.
- SMB package is JEDEC registered (DO-214AA).
- Trisils comply with the following standards:
 - GR-1089 Core
 - ITU-T-K20/K21
 - VDE0433
 - VDE0878
 - IEC 61000-4-5
 - FCC part 68

Applications

Any sensitive equipment requiring protection against lightning strikes and power crossing:

- Ethernet,
- T1/E1

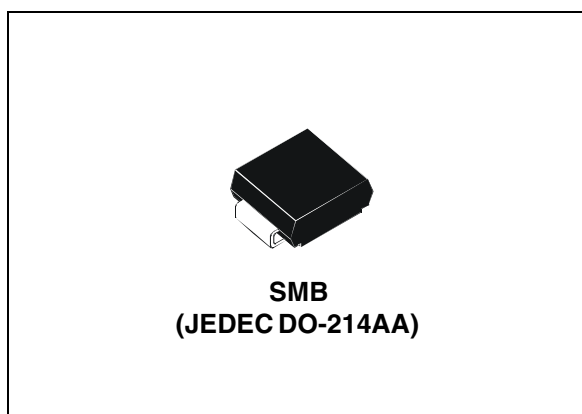
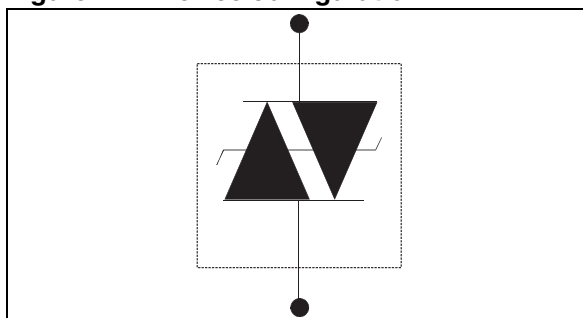


Figure 1. Device configuration



Description

The SMP75 is a very low voltage transient surge arrester especially designed to protect sensitive telecommunication equipment against lightning strikes and other transients. Its low voltage makes it suitable to protect low voltage transformer in T1/E1 and Ethernet links without saturation of the transformer.

TM: Trisil is a trademark of STMicroelectronics.

Characteristics

SMP75

1 Characteristics

Table 1. In compliance with the following standards

Standard	Peak surge voltage (V)	Waveform voltage	Required peak current (A)	Current waveform	Minimum serial resistor to meet standard (Ω)
GR-1089 Core First level	2500 1000	2/10 μ s 10/1000 μ s	500 100	2/10 μ s 10/1000 μ s	5 3.3
GR-1089 Core Second level	5000	2/10 μ s	500	2/10 μ s	10
GR-1089 Core Intra-building	1500	2/10 μ s	100	2/10 μ s	0
ITU-T-K20/K21	6000 1500	10/700 μ s	150 37.5	5/310 μ s	10 0
ITU-T-K20 (IEC61000-4-2)	8000 15000	1/60 ns	ESD contact discharge ESD air discharge		0 0
VDE0433	4000 2000	10/700 μ s	100 50	5/310 μ s	0 0
VDE0878	4000 2000	1.2/50 μ s	100 50	1/20 μ s	0 0
IEC61000-4-5	4000 4000	10/700 μ s 1.2/50 μ s	100 100	5/310 μ s 8/20 μ s	0 0
FCC Part 68, lightning surge type A	1500 800	10/160 μ s 10/560 μ s	200 100	10/160 μ s 10/560 μ s	2.5 0
FCC Part 68, lightning surge type B	1000	9/720 μ s	25	5/320 μ s	0

SMP75

Characteristics

Table 2. Absolute ratings ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Parameter	Value	Unit
I_{PP}	Repetitive peak pulse current	10/1000 μs 8/20 μs 10/560 μs 5/310 μs 10/160 μs 1/20 μs 2/10 μs	75 250 100 120 150 250 250 A
I_{FS}	Fail-safe mode : maximum current ⁽¹⁾	8/20 μs	5 kA
I_{TSM}	Non repetitive surge peak on-state current (sinusoidal)	t = 0.2 s t = 1 s t = 2 s t = 15 mn	14 8 6.5 2 A
I^2t	I^2t value for using	t = 16.6 ms t = 20 ms	12 12.2 A ² s
T_{stg}	Storage temperature range	-55 to + 150	$^{\circ}\text{C}$
T_j	Maximum junction temperature	150	$^{\circ}\text{C}$
T_L	Maximum lead temperature for soldering during 10 s.	260	$^{\circ}\text{C}$

1. In fail safe mode, the device acts as a short circuit.

Table 3. Thermal resistances

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient (with recommended footprint)	100	$^{\circ}\text{C/W}$
$R_{th(j-l)}$	Junction to leads	20	$^{\circ}\text{C/W}$

Table 4. Electrical characteristics - definitions ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Parameter	
V_{RM}	Stand-off voltage	
V_{BR}	Breakdown voltage	
V_{BO}	Breakover voltage	
I_{RM}	Leakage current	
I_{PP}	Peak pulse current	
I_{BO}	Breakover current	
I_H	Holding current	
V_R	Continuous reverse voltage	
I_R	Leakage current at V_R	
C	Capacitance	

Characteristics

SMP75

Table 5. Electrical characteristics - values ($T_{amb} = 25^\circ\text{C}$)

Order code	$I_{RM} @ V_{RM}$		$I_R^{(1)} @ V_R$		Dynamic V_{BO}	Static $V_{BO} @ I_{BO}$		I_H	$C^{(2)}$
	max.		max.		max.	max.	max.	typ.	max.
	μA	V	μA	V	V	V	mA	mA	pF
SMP75-8	2	6	5	8	20	15	800	50	60

1. I_R measured at V_R guaranteed $V_{BR} \min \geq V_R$

2. $V_R = 2\text{ V}$ bias, $V_{RMS} = 1\text{ V}$, $F = 1\text{ MHz}$

Figure 2. Pulse waveform

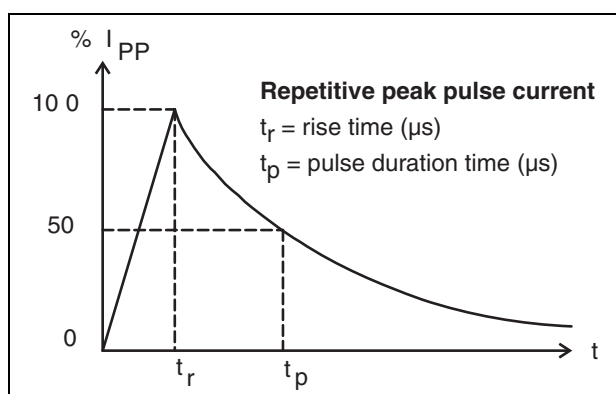


Figure 3. Non repetitive surge peak on-state current versus overload duration

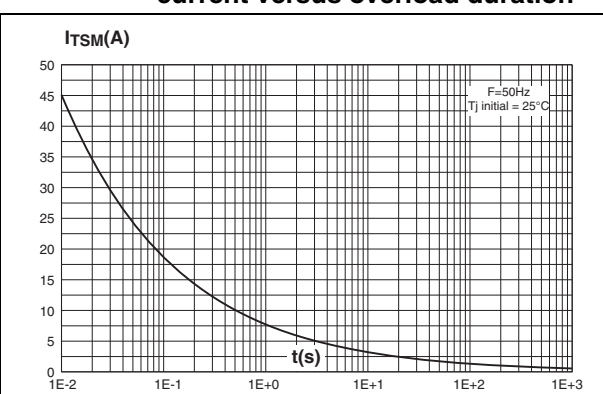


Figure 4. On-state voltage versus on-state current (typical values)

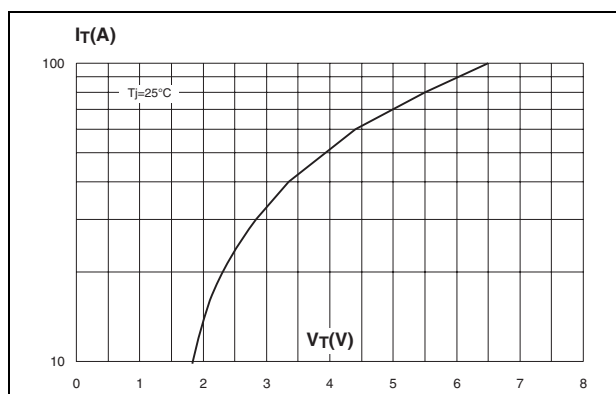
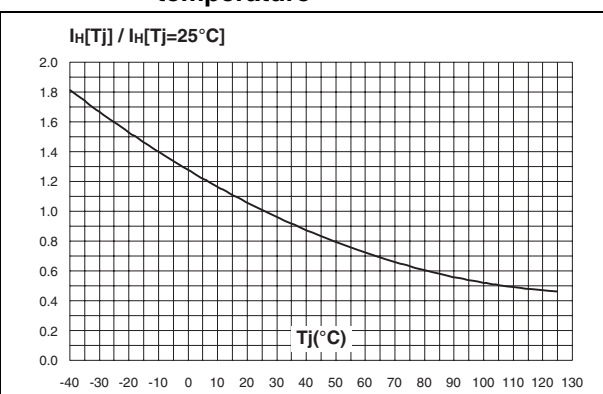


Figure 5. Relative variation of holding current versus junction temperature



SMP75

Characteristics

Figure 6. Relative variation of breakover voltage versus junction temperature

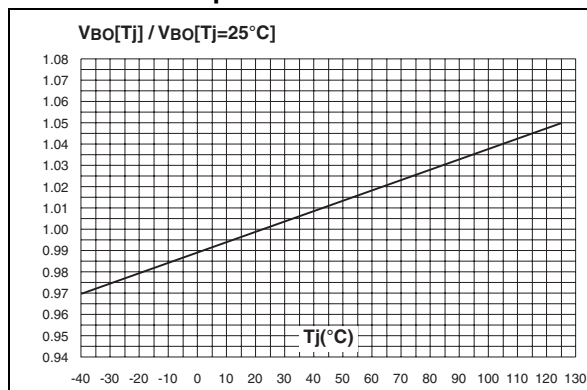


Figure 7. Relative variation of leakage current versus reverse voltage applied (typical values)

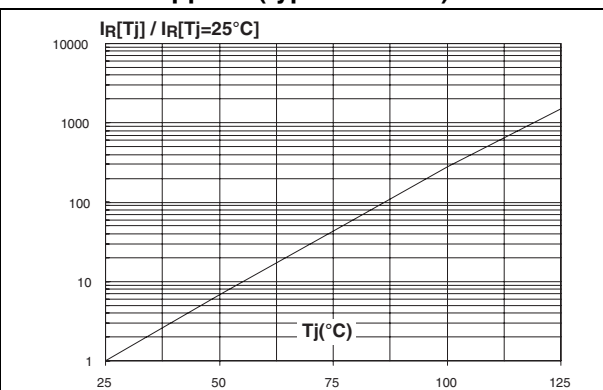


Figure 8. Variation of thermal impedance junction to ambient versus pulse duration

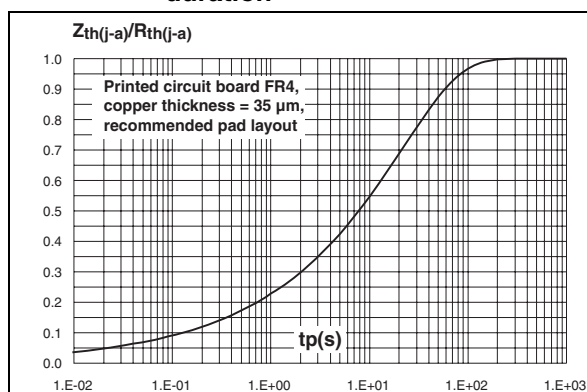
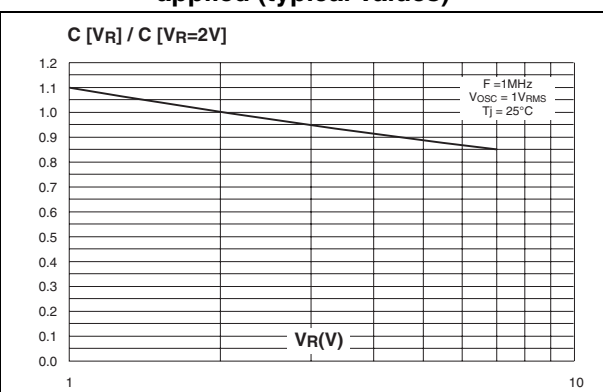
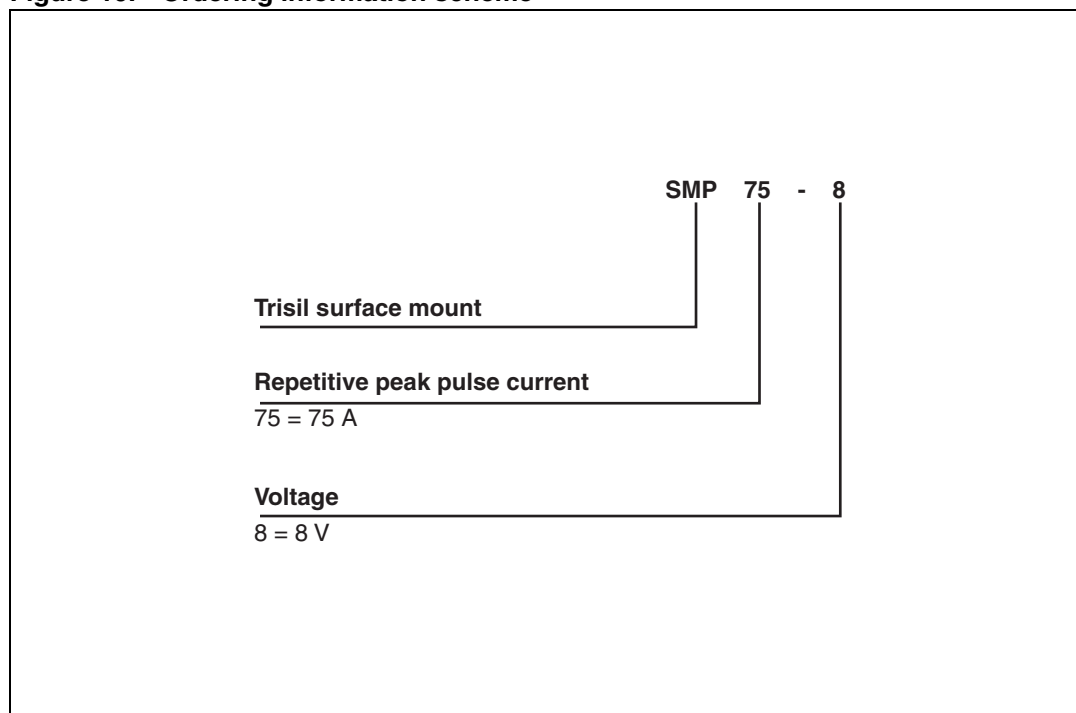


Figure 9. Relative variation of junction capacitance versus reverse voltage applied (typical values)



2 Ordering information scheme

Figure 10. Ordering information scheme



SMP75

Package information

3 Package information

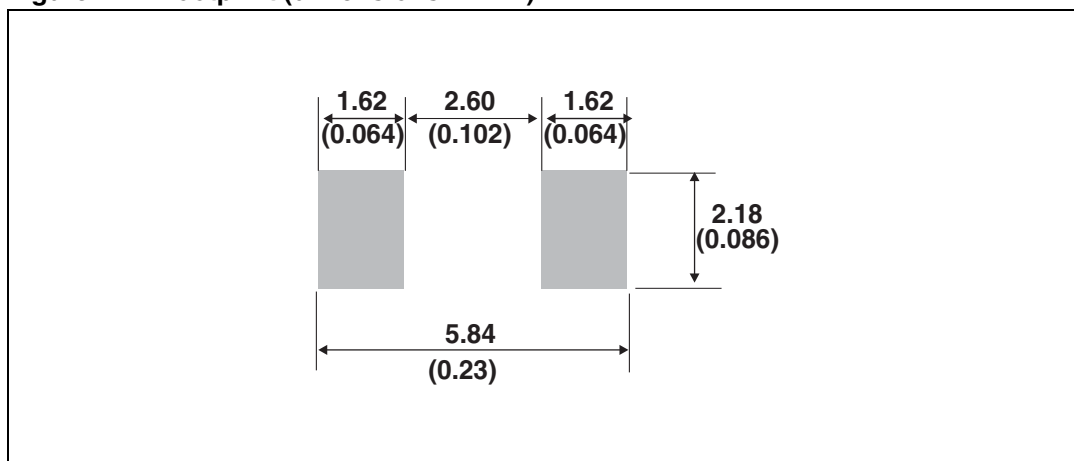
- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

Table 6. SMB Dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.40	0.006	0.016
D	3.30	3.95	0.130	0.156
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
L	0.75	1.50	0.030	0.059

Figure 11. Footprint (dimensions in mm)



Ordering information

SMP75

4 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
SMP75-8	L08	SMB	0.11 g	2500	Tape and reel

5 Revision history

Table 8. Document revision history

Date	Revision	Changes
19-July-2005	3	Previous issue
02-Jan-2006	4	Added ECOPACK statement and changed page layout. Minor updates to technical values in Tables 1, 2, and 4.
19-Oct-2010	5	Updated ECOPACK statement. Updated trademark statement. Updated Figure 11 . Removed Section 2 Test circuits.

SMP75

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